

Product Summary

| $V_{(BR)DSS}$ | $R_{DS(ON)} \text{ max}$ | $I_D \text{ max}$ $T_A = 25^\circ\text{C}$ |
|---------------|------------------------------|---|
| 20V | $0.99\Omega @ V_{GS} = 4.5V$ | 450mA |
| | $1.2\Omega @ V_{GS} = 2.5V$ | 400mA |
| | $1.8\Omega @ V_{GS} = 1.8V$ | 330mA |
| | $2.4\Omega @ V_{GS} = 1.5V$ | 300mA |

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions
- DC-DC Converters
- Analog Switch

Features and Benefits

- Dual N-Channel MOSFET
- Low On-Resistance
- Very low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface Mount Package 1mm x 1mm
- Low Package Profile, 0.45mm Maximum Package height
- ESD Protected Gate
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device, Halogen and Antimony Free (Note 2)**
- **Qualified to AEC-Q101 standards for High Reliability**

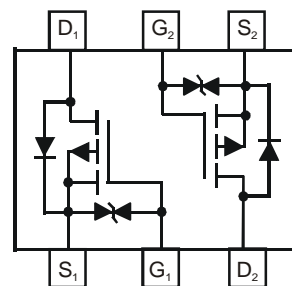
Mechanical Data

- Case: SOT963
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish — Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.027 grams (approximate)

SOT963



Top View



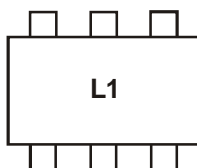
Top View
Schematic and Transistor Diagram

Ordering Information (Note 3)

| Part Number | Case | Packaging |
|--------------|--------|-----------------|
| DMN2990UDJ-7 | SOT963 | 10K/Tape & Reel |

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



L1 = Product Type Marking Code

Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | | | Symbol | Value | Units |
|--|--------------|-----------------------|------------------|-------|-------|
| Drain-Source Voltage | | | V _{DSS} | 20 | V |
| Gate-Source Voltage | | | V _{GSS} | ±8 | V |
| Continuous Drain Current (Note 4) V _{GS} = 4.5V | Steady State | T _A = 25°C | I _D | 450 | mA |
| | | T _A = 70°C | | 350 | |
| Continuous Drain Current (Note 4) V _{GS} = 1.8V | Steady State | T _A = 25°C | I _D | 330 | mA |
| | | T _A = 70°C | | 220 | |
| Pulsed Drain Current (Note 5) | | | I _{DM} | 800 | mA |

Thermal Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Units |
|---|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 4) | P _D | 350 | mW |
| Thermal Resistance, Junction to Ambient | R _{θJA} | 360 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|---------------------|-----|------|------|------|---|
| OFF CHARACTERISTICS (Note 6) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 20 | - | - | V | V _{GS} = 0V, I _D = 250μA |
| Zero Gate Voltage Drain Current @T _c = 25°C | I _{DSS} | - | - | 50 | nA | V _{DS} = 5V, V _{GS} = 0V |
| | | - | - | 100 | | V _{DS} = 16V, V _{GS} = 0V |
| Gate-Source Leakage | I _{GSS} | - | - | ±100 | nA | V _{GS} = ±5V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 6) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 0.4 | - | 1.0 | V | V _{DS} = V _{GS} , I _D = 250μA |
| Static Drain-Source On-Resistance | R _{DS(on)} | - | 0.60 | 0.99 | Ω | V _{GS} = 4.5V, I _D = 100mA |
| | | - | 0.75 | 1.2 | | V _{GS} = 2.5V, I _D = 50mA |
| | | - | 0.90 | 1.8 | | V _{GS} = 1.8V, I _D = 20mA |
| | | - | 1.2 | 2.4 | | V _{GS} = 1.5V, I _D = 10mA |
| | | - | 2.0 | - | | V _{GS} = 1.2V, I _D = 1mA |
| | | - | - | - | | V _{GS} = 1.0V, I _D = 1mA |
| Forward Transfer Admittance | Y _{fs} | 180 | - | - | mS | V _{DS} = 10V, I _D = 400mA |
| Diode Forward Voltage (Note 6) | V _{SD} | - | 0.6 | 1.0 | V | V _{GS} = 0V, I _S = 150mA |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | |
| Input Capacitance | C _{iss} | - | 27.6 | - | pF | V _{DS} = 16V, V _{GS} = 0V, f = 1.0MHz |
| Output Capacitance | C _{oss} | - | 4.0 | - | pF | |
| Reverse Transfer Capacitance | C _{rss} | - | 2.8 | - | pF | |
| Total Gate Charge | Q _g | - | 0.5 | - | nC | V _{GS} = 4.5V, V _{DS} = 10V, I _D = 250mA |
| Gate-Source Charge | Q _{gs} | - | 0.07 | - | nC | |
| Gate-Drain Charge | Q _{gd} | - | 0.07 | - | nC | |
| Turn-On Delay Time | t _{D(on)} | - | 4.0 | - | ns | V _{DD} = 10V, V _{GS} = 4.5V, R _L = 47Ω, R _G = 10Ω, I _D = 200mA |
| Turn-On Rise Time | t _r | - | 3.3 | - | ns | |
| Turn-Off Delay Time | t _{D(off)} | - | 19.0 | - | ns | |
| Turn-Off Fall Time | t _f | - | 6.4 | - | ns | |

- Notes: 4. Device mounted on FR-4 PCB, with minimum recommended pad layout.
5. Device mounted on minimum recommended pad layout test board, 10μs pulse duty cycle = 1%.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

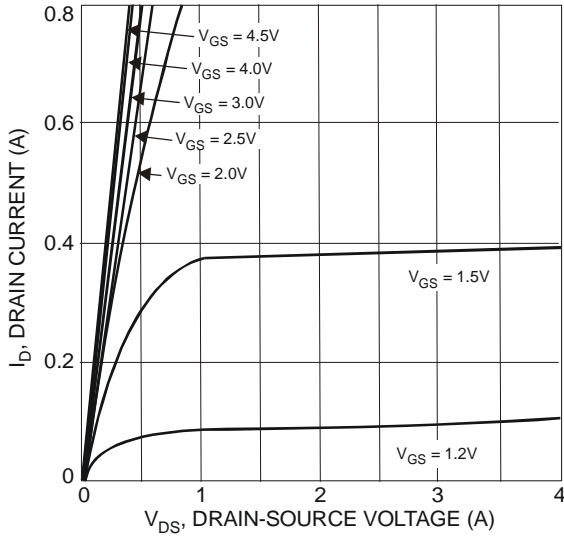


Fig. 1 Typical Output Characteristics

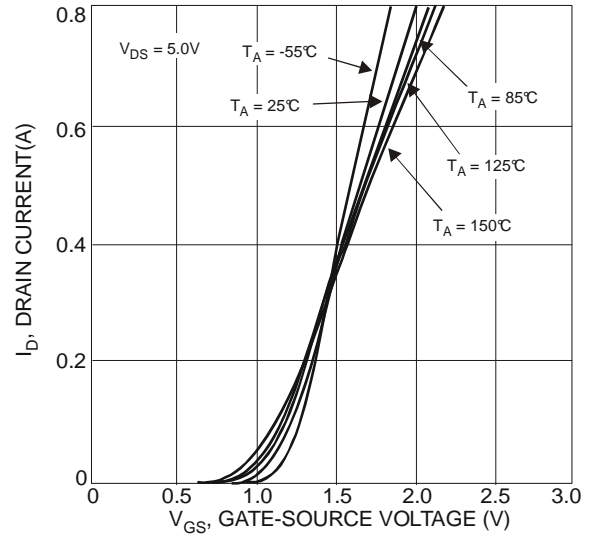


Fig. 2 Typical Transfer Characteristics

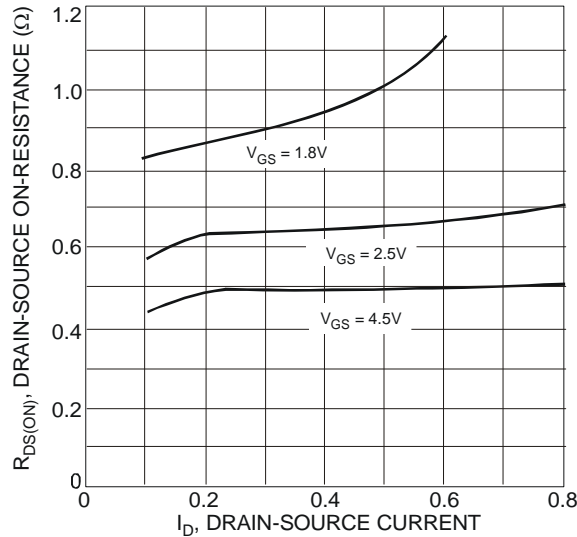


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

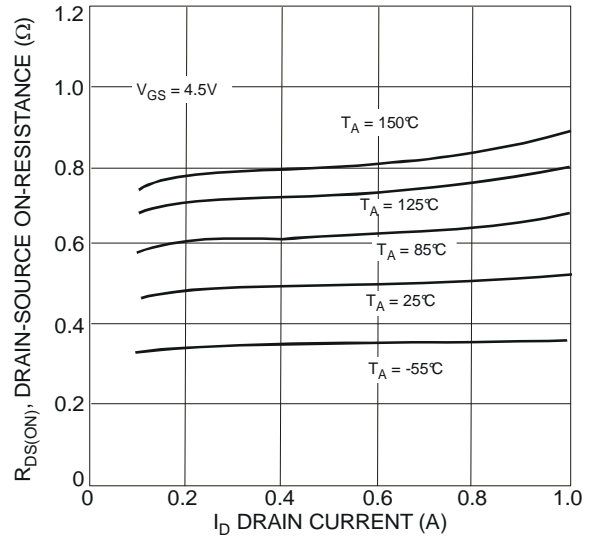


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

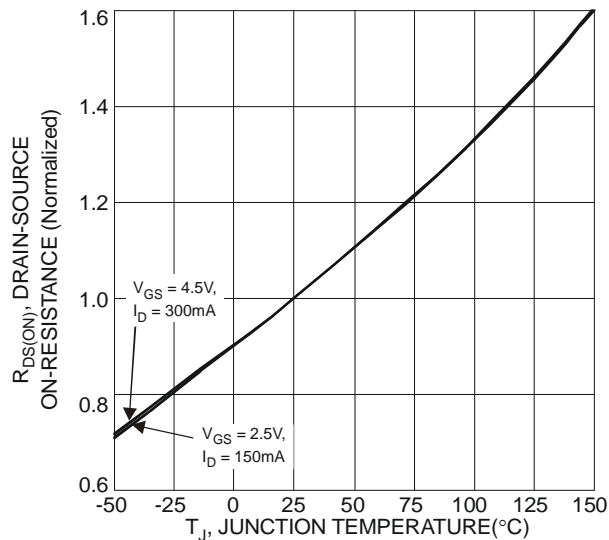


Fig. 5 On-Resistance Variation with Temperature

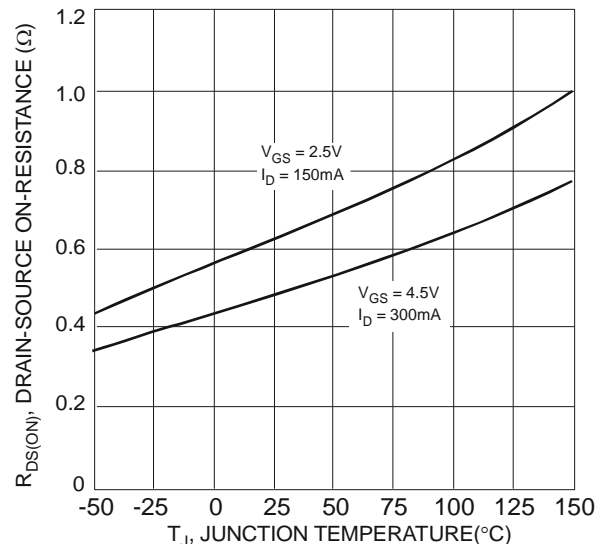


Fig. 6 On-Resistance Variation with Temperature

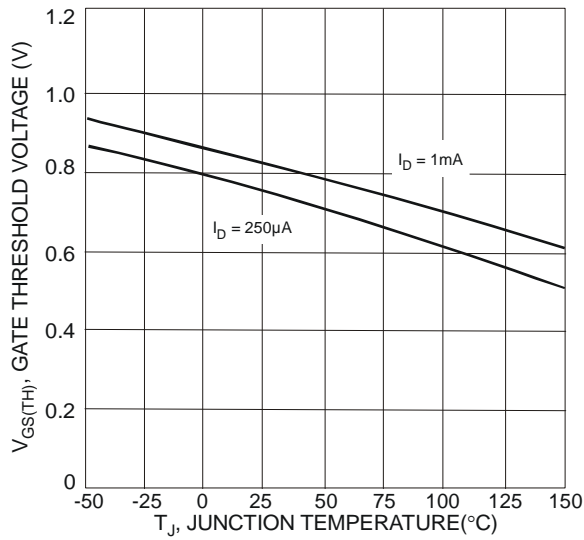


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

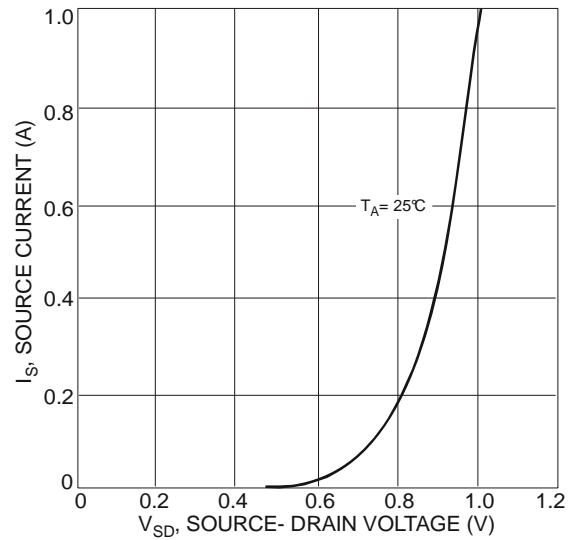


Fig. 8 Diodes Forward Voltage vs. Current

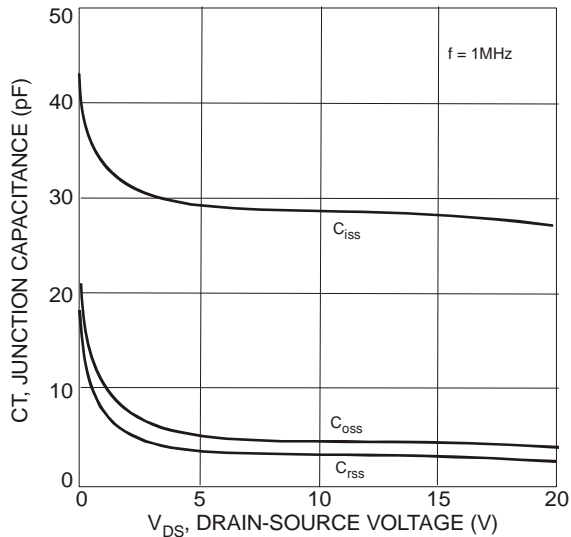


Fig. 9 Typical Junction Capacitance

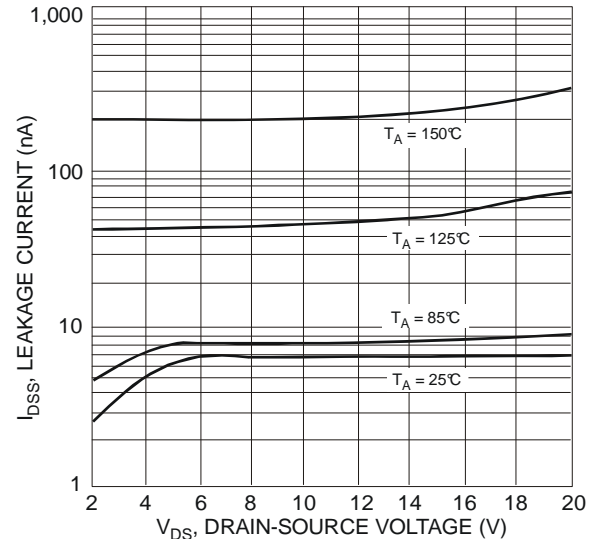


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

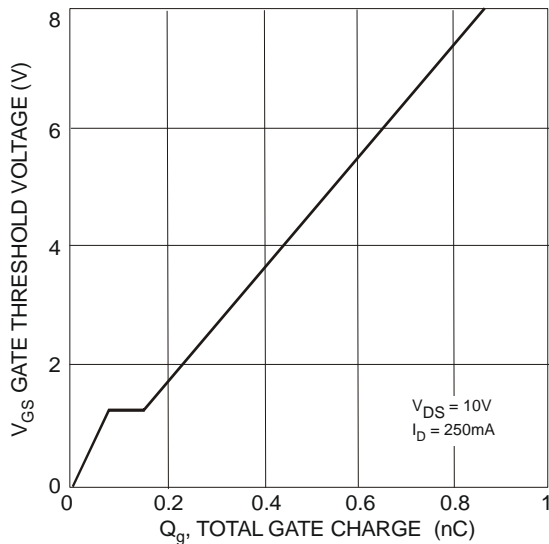


Fig. 11 Gate Charge

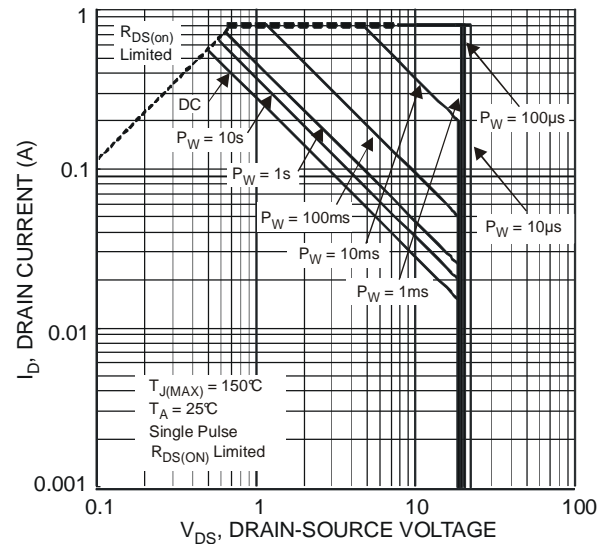
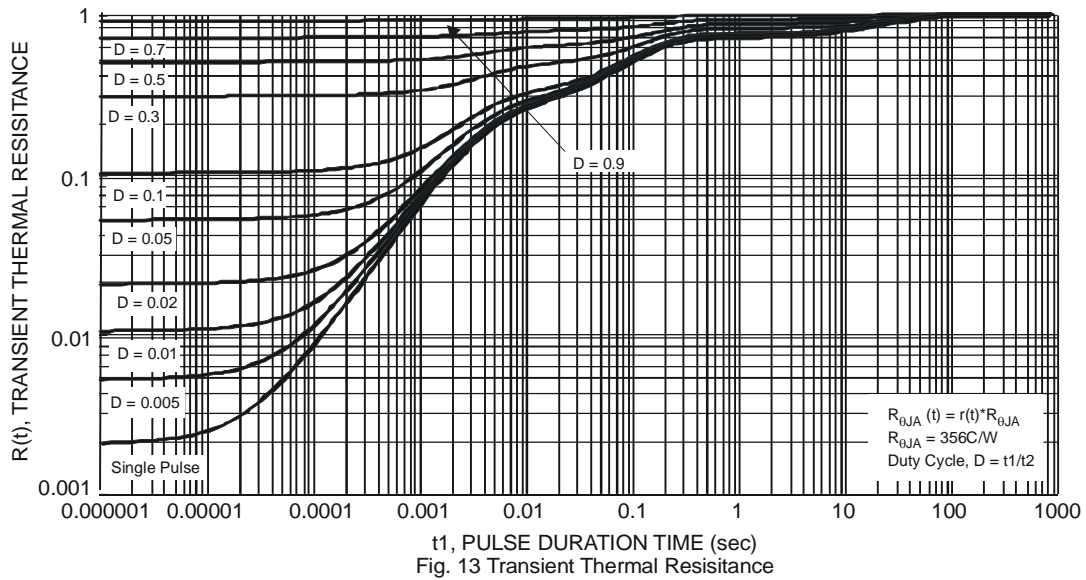
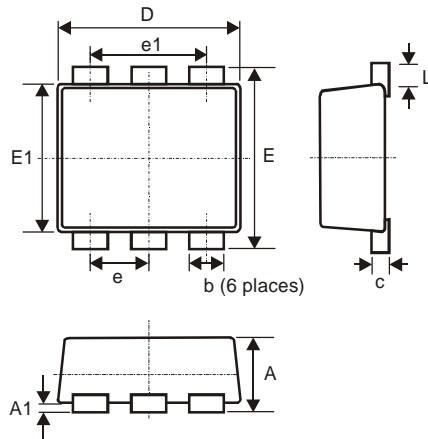


Fig. 12 SOA, Safe Operation Area

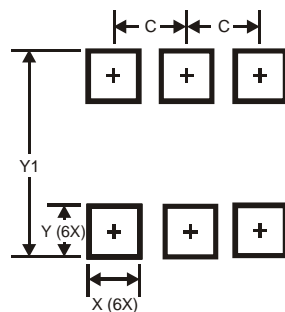


Package Outline Dimensions



| SOT963 | | | |
|----------------------|----------|-------|-------|
| Dim | Min | Max | Typ |
| A | 0.40 | 0.50 | 0.45 |
| A1 | 0 | 0.05 | - |
| c | 0.120 | 0.180 | 0.150 |
| D | 0.95 | 1.05 | 1.00 |
| E | 0.95 | 1.05 | 1.00 |
| E1 | 0.75 | 0.85 | 0.80 |
| L | 0.05 | 0.15 | 0.10 |
| b | 0.10 | 0.20 | 0.15 |
| e | 0.35 Typ | | |
| e1 | 0.70 Typ | | |
| All Dimensions in mm | | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.350 |
| X | 0.200 |
| Y | 0.200 |
| Y1 | 1.100 |

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